



52



14



30

**DEPARTMENTS**

	AEI NEWS	08
	IN VIEW THIS MONTH	10
	COMPANY ON THE MOVE	48
	BUSINESS STRATEGY	51
	PRODUCT NEWS	58

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**SPECIAL REPORT**

New PCB Designs Emerge to Improve Characteristics	12
Latest PCB Technologies Catch up on Industry Developments	13
Electronic Materials Support 5G-Compatible PCBs	15
Electronic Parts Makers Seize Potentials of IoT Market	16

**TECH FOCUS**

Latest R&D Trends and Future Developments of 5G Technology	17
KDDI Outlines Efforts Toward Building New 5G Society	19
5G Undergoes Overall System Test in Truck Platooning	21
Private 4G/5G Networks Make Big Impacts on Social Infrastructure	25
Resonant MLCC for High-Power Wireless Charging	28
Aluminum Electrolytic Capacitors Advance in Rated Voltage for Industrial Use	30
High-Reliability DLCAP EDLCs Rev up for Automotives	32

**COMPONENT MATERIALS**

	35
--	----

**SMTs: IN REVIEW**

	38
--	----

**TEST AND MEASUREMENT**

	40
--	----

**TECHNOLOGY HIGHLIGHT**

Interlayered Perovskites Create Ultrathin OLED for Large Displays	41
Technology Yields Higher-Efficiency GaN Micro LEDs	42
Multi-Layered Metals Heighten Sensitivity of Motion Sensors	43

**PRODUCT HIGHLIGHT**

Flexible Sensor Material Suits Upmarket Automotive Touch Panels	45
ROHM Employs Unique Process in Automotive-Grade MOSFETs	46

**ZOOM-IN**

	47
--	----

**TOP INTERVIEW**

	49
--	----

**COMPANY PROFILE**

	50
--	----

**SHOW REPORT**

NEPCON Asia 2019	52
NEPCON Vietnam 2019	54
productronica India 2019	55
SEMICON Taiwan 2019	56